



**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**In re Application of:**

**Cobbley et al.**

**Serial No.:** 10/693,286

**Filed:** October 23, 2003

**For:** METHOD FOR MANUFACTURING  
FLIP-CHIP SEMICONDUCTOR  
ASSEMBLY

**Confirmation No.:** 2348

**Examiner:** T. Nguyen

**Group Art Unit:** 2813

**Attorney Docket No.:** 2269-3437.7US  
(97-0514.07/US)

**Notice of Allowance Mailed:**

January 11, 2005

**NOTICE OF EXPRESS MAILING**

Express Mail Mailing Label Number: EL994823379US

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Person making Deposit: Steve Wong

**AMENDMENT PURSUANT TO 37 C.F.R. § 1.312(a)**

Mail Stop ISSUE FEE  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, Virginia 22313-1450

Sir:

Please amend the above-referenced application as follows:

**Amendments to the Claims** are reflected in the listing of claims which begins on page 2 of this paper.

**Remarks** begin on page 5 of this paper.